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Embedded - System On Chip (SoC): The Heart of Modern Embedded Systems

Embedded - System On Chip (SoC) refers to an integrated circuit that consolidates all the essential components of a computer system into a single chip. This includes a microprocessor, memory, and other peripherals, all packed into one compact and efficient package. SoCs are designed to provide a complete computing solution, optimizing both space and power consumption, making them ideal for a wide range of embedded applications.

What are **Embedded - System On Chip (SoC)**?

System On Chip (SoC) integrates multiple functions of a computer or electronic system onto a single chip. Unlike traditional multi-chip solutions. SoCs combine a central

Details	
Product Status	Discontinued at Digi-Key
Architecture	MCU, FPGA
Core Processor	Dual ARM® Cortex®-A9 MPCore™ with CoreSight™
Flash Size	-
RAM Size	256KB
Peripherals	DMA, POR, WDT
Connectivity	EBI/EMI, Ethernet, I ² C, MMC/SD/SDIO, SPI, UART/USART, USB OTG
Speed	1.5GHz
Primary Attributes	FPGA - 270K Logic Elements
Operating Temperature	0°C ~ 100°C (TJ)
Package / Case	780-BBGA, FCBGA
Supplier Device Package	780-FBGA, FC (29x29)
Purchase URL	https://www.e-xfl.com/product-detail/intel/10as027e1f29e1sg

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong



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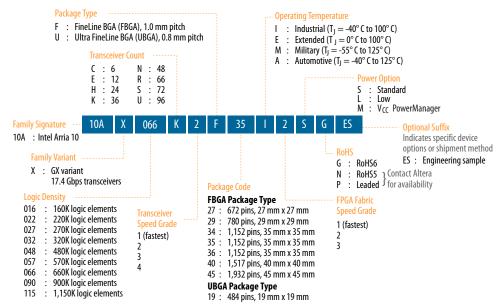
Feature		Description
Low-power serial transceivers	- Intel Arria 10 GT- Backplane support: - Intel Arria 10 GX- Intel Arria 10 GT- Extended range dow ATX transmit PLLs w Electronic Dispersion module Adaptive linear and of	—1 Gbps to 17.4 Gbps —1 Gbps to 25.8 Gbps —up to 12.5
HPS (Intel Arria 10 SX devices only)	Processor and system	Dual-core ARM Cortex-A9 MPCore processor—1.2 GHz CPU with 1.5 GHz overdrive capability 256 KB on-chip RAM and 64 KB on-chip ROM System peripherals—general-purpose timers, watchdog timers, direct memory access (DMA) controller, FPGA configuration manager, and clock and reset managers Security features—anti-tamper, secure boot, Advanced Encryption Standard (AES) and authentication (SHA) ARM CoreSight* JTAG debug access port, trace port, and on-chip trace storage
	External interfaces	Hard memory interface—Hard memory controller (2,400 Mbps DDR4, and 2,133 Mbps DDR3), Quad serial peripheral interface (QSPI) flash controller, NAND flash controller, direct memory access (DMA) controller, Secure Digital/MultiMediaCard (SD/MMC) controller Communication interface— 10/100/1000 Ethernet media access control (MAC), USB On-The-GO (OTG) controllers, I²C controllers, UART 16550, serial peripheral interface (SPI), and up to 62 HPS GPIO interfaces (48 direct-share I/Os)
	Interconnects to core	High-performance ARM AMBA* AXI bus bridges that support simultaneous read and write HPS-FPGA bridges—include the FPGA-to-HPS, HPS-to-FPGA, and lightweight HPS-to-FPGA bridges that allow the FPGA fabric to issue transactions to slaves in the HPS, and vice versa Configuration bridge that allows HPS configuration manager to configure the core logic via dedicated 32-bit configuration port FPGA-to-HPS SDRAM controller bridge—provides configuration interfaces for the multiport front end (MPFE) of the HPS SDRAM controller
Configuration	Enhanced 256-bit ad	comprehensive design protection to protect your valuable IP investments dvanced encryption standard (AES) design security with authentication obtocol (CvP) using PCIe Gen1, Gen2, or Gen3
		continued

 $^{^{(2)}}$ Intel Arria 10 devices support this external memory interface using hard PHY with soft memory controller.



Available Options

Figure 1. Sample Ordering Code and Available Options for Intel Arria 10 GX Devices



Related Information

Transceiver Performance for Intel Arria 10 GX/SX Devices

Provides more information about the transceiver speed grade.



Table 6. Maximum Resource Counts for Intel Arria 10 GX Devices (GX 570, GX 660, GX 900, and GX 1150)

Re	source		Produc	t Line	
		GX 570	GX 660	GX 900	GX 1150
Logic Elements	s (LE) (K)	570	660	900	1,150
ALM		217,080	251,680	339,620	427,200
Register		868,320	1,006,720	1,358,480	1,708,800
Memory (Kb)	M20K	36,000	42,620	48,460	54,260
	MLAB	5,096	5,788	9,386	12,984
Variable-precis	sion DSP Block	1,523	1,687	1,518	1,518
18 x 19 Multip	lier	3,046	3,374	3,036	3,036
PLL	Fractional Synthesis	16	16	32	32
	I/O	16	16	16	16
17.4 Gbps Trai	nsceiver	48	48	96	96
GPIO (3)		696	696	768	768
LVDS Pair (4)		324	324	384	384
PCIe Hard IP Block		2	2	4	4
Hard Memory	Controller	16	16	16	16

Package Plan

Table 7. Package Plan for Intel Arria 10 GX Devices (U19, F27, and F29)

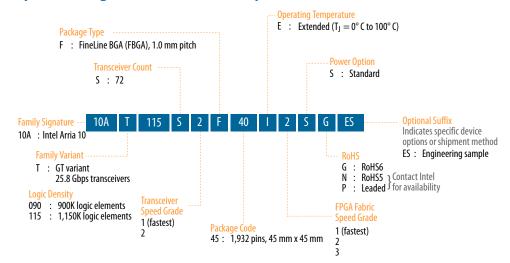
Refer to I/O and High Speed I/O in Intel Arria 10 Devices chapter for the number of 3 V I/O, LVDS I/O, and LVDS channels in each device package.

Product Line	U19 (19 mm × 19 mm, 484-pin UBGA)				F27 mm × 27 n 72-pin FBG/			F29 mm × 29 n 80-pin FBG/	
	3 V I/O	LVDS I/O	XCVR	3 V I/O	3 V I/O LVDS I/O XCVR			LVDS I/O	XCVR
GX 160	48	192	6	48	192	12	48	240	12
GX 220	48	192	6	48	192	12	48	240	12
GX 270	_	_	_	48	192	12	48	312	12
GX 320	_	_	_	48	192	12	48	312	12
GX 480	_	_	_	_	_	_	48	312	12



Available Options

Figure 2. Sample Ordering Code and Available Options for Intel Arria 10 GT Devices





Maximum Resources

Table 10. Maximum Resource Counts for Intel Arria 10 GT Devices

Reso	ource	Produc	ct Line	
		GT 900	GT 1150	
Logic Elements (LE) (K)		900	1,150	
ALM		339,620	427,200	
Register		1,358,480	1,708,800	
Memory (Kb)	M20K	48,460	54,260	
	MLAB	9,386	12,984	
Variable-precision DSP Block		1,518	1,518	
18 x 19 Multiplier		3,036	3,036	
PLL	Fractional Synthesis	32	32	
	I/O	16	16	
Transceiver	17.4 Gbps	72 ⁽⁵⁾	72 ⁽⁵⁾	
	25.8 Gbps	6	6	
GPIO ⁽⁶⁾		624	624	
LVDS Pair ⁽⁷⁾		312	312	
PCIe Hard IP Block		4	4	
Hard Memory Controller		16	16	

Related Information

Intel Arria 10 GT Channel Usage

Configuring GT/GX channels in Intel Arria 10 GT devices.

Package Plan

Table 11. Package Plan for Intel Arria 10 GT Devices

Refer to I/O and High Speed I/O in Intel Arria 10 Devices chapter for the number of 3 V I/O, LVDS I/O, and LVDS channels in each device package.

Product Line	SF45 (45 mm × 45 mm, 1932-pin FBGA)					
	3 V I/O	LVDS I/O	XCVR			
GT 900	_	624	72			
GT 1150	_	624	72			

⁽⁵⁾ If all 6 GT channels are in use, 12 of the GX channels are not usable.

⁽⁶⁾ The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.

⁽⁷⁾ Each LVDS I/O pair can be used as differential input or output.



Maximum Resources

Table 12. Maximum Resource Counts for Intel Arria 10 SX Devices

Reso	ource			I	Product Line			
		SX 160	SX 220	SX 270	SX 320	SX 480	SX 570	SX 660
Logic Elements	s (LE) (K)	160	220	270	320	480	570	660
ALM		61,510	80,330	101,620	119,900	183,590	217,080	251,680
Register		246,040	321,320	406,480	479,600	734,360	868,320	1,006,720
Memory (Kb)	M20K	8,800	11,740	15,000	17,820	28,620	36,000	42,620
	MLAB	1,050	1,690	2,452	2,727	4,164	5,096	5,788
Variable-precis	sion DSP Block	156	192	830	985	1,368	1,523	1,687
18 x 19 Multip	lier	312	384	1,660	1,970	2,736	3,046	3,374
PLL	Fractional Synthesis	6	6	8	8	12	16	16
	I/O	6	6	8	8	12	16	16
17.4 Gbps Tra	nsceiver	12	12	24	24	36	48	48
GPIO (8)		288	288	384	384	492	696	696
LVDS Pair (9)		120	120	168	168	174	324	324
PCIe Hard IP E	Block	1	1	2	2	2	2	2
Hard Memory	Controller	6	6	8	8	12	16	16
ARM Cortex-As	9 MPCore	Yes	Yes	Yes	Yes	Yes	Yes	Yes

Package Plan

Table 13. Package Plan for Intel Arria 10 SX Devices (U19, F27, F29, and F34)

Refer to I/O and High Speed I/O in Intel Arria 10 Devices chapter for the number of 3 V I/O, LVDS I/O, and LVDS channels in each device package.

Product Line	U19 (19 mm × 19 mm, 484-pin UBGA)		F27 (27 mm × 27 mm, 672-pin FBGA)			F29 (29 mm × 29 mm, 780-pin FBGA)			F34 (35 mm × 35 mm, 1152-pin FBGA)			
	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR
SX 160	48	144	6	48	192	12	48	240	12	_	_	_
SX 220	48	144	6	48	192	12	48	240	12	_	_	_
SX 270	_	_	_	48	192	12	48	312	12	48	336	24
SX 320	_	_	_	48	192	12	48	312	12	48	336	24
											contii	nued

 $^{^{(8)}}$ The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.

⁽⁹⁾ Each LVDS I/O pair can be used as differential input or output.



I/O Vertical Migration for Intel Arria 10 Devices

Figure 4. Migration Capability Across Intel Arria 10 Product Lines

- The arrows indicate the migration paths. The devices included in each vertical migration path are shaded. Devices with fewer resources in the same path have lighter shades.
- To achieve the full I/O migration across product lines in the same migration path, restrict I/Os and transceivers usage to match the product line with the lowest I/O and transceiver counts.
- An LVDS I/O bank in the source device may be mapped to a 3 V I/O bank in the target device. To use
 memory interface clock frequency higher than 533 MHz, assign external memory interface pins only to
 banks that are LVDS I/O in both devices.
- There may be nominal 0.15 mm package height difference between some product lines in the same package type.
- Some migration paths are not shown in the Intel Quartus Prime software Pin Migration View.

Variant	Product						Package	e				
variant	Line	U19	F27	F29	F34	F35	KF40	NF40	RF40	NF45	SF45	UF45
	GX 160	1	1	1								
	GX 220	+										
	GX 270				1	1						
	GX 320		V									
Intel® Arria® 10 GX	GX 480			V								
	GX 570						1	1				
	GX 660					V	\					
	GX 900								1	1		1
	GX 1150				V			+	+	+		+
Intel Arria 10 GT	GT 900											
intel Afria 10 G1	GT 1150										V	
	SX 160	1	1	1								
	SX 220	+										
	SX 270				1	†						
Intel Arria 10 SX	SX 320		V									
	SX 480			V								
	SX 570						†	†				
	SX 660				V							

Note:

To verify the pin migration compatibility, use the **Pin Migration View** window in the Intel Quartus Prime software Pin Planner.

Adaptive Logic Module

Intel Arria 10 devices use a 20 nm ALM as the basic building block of the logic fabric.

The ALM architecture is the same as the previous generation FPGAs, allowing for efficient implementation of logic functions and easy conversion of IP between the device generations.

The ALM, as shown in following figure, uses an 8-input fracturable look-up table (LUT) with four dedicated registers to help improve timing closure in register-rich designs and achieve an even higher design packing capability than the traditional two-register per LUT architecture.



Features for floating-point arithmetic:

- A completely hardened architecture that supports multiplication, addition, subtraction, multiply-add, and multiply-subtract
- Multiplication with accumulation capability and a dynamic accumulator reset control
- Multiplication with cascade summation capability
- Multiplication with cascade subtraction capability
- Complex multiplication
- Direct vector dot product
- Systolic FIR filter

Table 15. Variable-Precision DSP Block Configurations for Intel Arria 10 Devices

Usage Example	Multiplier Size (Bit)	DSP Block Resources
Medium precision fixed point	Two 18 x 19	1
High precision fixed or Single precision floating point	One 27 x 27	1
Fixed point FFTs	One 19 x 36 with external adder	1
Very high precision fixed point	One 36 x 36 with external adder	2
Double precision floating point	One 54 x 54 with external adder	4

Table 16. Resources for Fixed-Point Arithmetic in Intel Arria 10 Devices

The table lists the variable-precision DSP resources by bit precision for each Intel Arria 10 device.

Variant	Product Line	Variable- precision DSP Block		nput and Output ons Operator	18 x 19 Multiplier Adder Sum	18 x 18 Multiplier Adder
		DSP BIOCK	18 x 19 Multiplier	27 x 27 Multiplier	Mode Mode	Summed with 36 bit Input
AIntel Arria 10	GX 160	156	312	156	156	156
GX	GX 220	192	384	192	192	192
	GX 270	830	1,660	830	830	830
	GX 320	984	1,968	984	984	984
	GX 480	1,368	2,736	1,368	1,368	1,368
	GX 570	1,523	3,046	1,523	1,523	1,523
	GX 660	1,687	3,374	1,687	1,687	1,687
	GX 900	1,518	3,036	1,518	1,518	1,518
	GX 1150	1,518	3,036	1,518	1,518	1,518
Intel Arria 10 GT	GT 900	1,518	3,036	1,518	1,518	1,518
GI	GT 1150	1,518	3,036	1,518	1,518	1,518
Intel Arria 10	SX 160	156	312	156	156	156
SX	SX 220	192	384	192	192	192
	SX 270	830	1,660	830	830	830
						continued



The fractional synthesis PLLs support the following features:

- Reference clock frequency synthesis for transceiver CMU and Advanced Transmit (ATX) PLLs
- Clock network delay compensation
- Zero-delay buffering
- Direct transmit clocking for transceivers
- Independently configurable into two modes:
 - Conventional integer mode equivalent to the general purpose PLL
 - Enhanced fractional mode with third order delta-sigma modulation
- PLL cascading

I/O PLLs

The integer mode I/O PLLs are located in each bank of 48 I/Os. You can use the I/O PLLs to simplify the design of external memory and high-speed LVDS interfaces.

In each I/O bank, the I/O PLLs are adjacent to the hard memory controllers and LVDS SERDES. Because these PLLs are tightly coupled with the I/Os that need to use them, it makes it easier to close timing.

You can use the I/O PLLs for general purpose applications in the core such as clock network delay compensation and zero-delay buffering.

Intel Arria 10 devices support PLL-to-PLL cascading.

FPGA General Purpose I/O

Intel Arria 10 devices offer highly configurable GPIOs. Each I/O bank contains 48 general purpose I/Os and a high-efficiency hard memory controller.

The following list describes the features of the GPIOs:

- Consist of 3 V I/Os for high-voltage application and LVDS I/Os for differential signaling
 - $-\$ Up to two 3 V I/O banks, available in some devices, that support up to 3 V I/O standards
 - LVDS I/O banks that support up to 1.8 V I/O standards
- Support a wide range of single-ended and differential I/O interfaces
- LVDS speeds up to 1.6 Gbps
- Each LVDS pair of pins has differential input and output buffers, allowing you to configure the LVDS direction for each pair.
- Programmable bus hold and weak pull-up
- Programmable differential output voltage (V_{OD}) and programmable pre-emphasis



Related Information

Intel Arria 10 Device Datasheet

Lists the memory interface performance according to memory interface standards, rank or chip select configurations, and Intel Arria 10 device speed grades.

PCIe Gen1, Gen2, and Gen3 Hard IP

Intel Arria 10 devices contain PCIe hard IP that is designed for performance and ease-of-use:

- Includes all layers of the PCIe stack—transaction, data link and physical layers.
- Supports PCIe Gen3, Gen2, and Gen1 Endpoint and Root Port in x1, x2, x4, or x8 lane configuration.
- Operates independently from the core logic—optional configuration via protocol (CvP) allows the PCIe link to power up and complete link training in less than 100 ms while the Intel Arria 10 device completes loading the programming file for the rest of the FPGA.
- Provides added functionality that makes it easier to support emerging features such as Single Root I/O Virtualization (SR-IOV) and optional protocol extensions.
- Provides improved end-to-end datapath protection using ECC.
- Supports FPGA configuration via protocol (CvP) using PCIe at Gen3, Gen2, or Gen1 speed.

Related Information

PCS Features on page 30

Enhanced PCS Hard IP for Interlaken and 10 Gbps Ethernet

Interlaken Support

The Intel Arria 10 enhanced PCS hard IP provides integrated Interlaken PCS supporting rates up to 25.8 Gbps per lane.

The Interlaken PCS is based on the proven functionality of the PCS developed for Intel's previous generation FPGAs, which demonstrated interoperability with Interlaken ASSP vendors and third-party IP suppliers. The Interlaken PCS is present in every transceiver channel in Intel Arria 10 devices.

Related Information

PCS Features on page 30

10 Gbps Ethernet Support

The Intel Arria 10 enhanced PCS hard IP supports 10GBASE-R PCS compliant with IEEE 802.3 10 Gbps Ethernet (10GbE). The integrated hard IP support for 10GbE and the 10 Gbps transceivers save external PHY cost, board space, and system power.



The scalable hard IP supports multiple independent 10GbE ports while using a single PLL for all the 10GBASE-R PCS instantiations, which saves on core logic resources and clock networks:

- Simplifies multiport 10GbE systems compared to XAUI interfaces that require an external XAUI-to-10G PHY.
- Incorporates Electronic Dispersion Compensation (EDC), which enables direct connection to standard 10 Gbps XFP and SFP+ pluggable optical modules.
- Supports backplane Ethernet applications and includes a hard 10GBASE-KR Forward Error Correction (FEC) circuit that you can use for 10 Gbps and 40 Gbps applications.

The 10 Gbps Ethernet PCS hard IP and 10GBASE-KR FEC are present in every transceiver channel.

Related Information

PCS Features on page 30

Low Power Serial Transceivers

Intel Arria 10 FPGAs and SoCs include lowest power transceivers that deliver high bandwidth, throughput and low latency.

Intel Arria 10 devices deliver the industry's lowest power consumption per transceiver channel:

- 12.5 Gbps transceivers at as low as 242 mW
- 10 Gbps transceivers at as low as 168 mW
- 6 Gbps transceivers at as low as 117 mW

Intel Arria 10 transceivers support various data rates according to application:

- Chip-to-chip and chip-to-module applications—from 1 Gbps up to 25.8 Gbps
- Long reach and backplane applications—from 1 Gbps up to 12.5 with advanced adaptive equalization
- Critical power sensitive applications—from 1 Gbps up to 11.3 Gbps using lower power modes

The combination of 20 nm process technology and architectural advances provide the following benefits:

- Significant reduction in die area and power consumption
- Increase of up to two times in transceiver I/O density compared to previous generation devices while maintaining optimal signal integrity
- Up to 72 total transceiver channels—you can configure up to 6 of these channels to run as fast as 25.8 Gbps
- All channels feature continuous data rate support up to the maximum rated speed



Each transceiver channel contains a channel PLL that can be used as the CMU PLL or clock data recovery (CDR) PLL. In CDR mode, the channel PLL recovers the receiver clock and data in the transceiver channel. Up to 80 independent data rates can be configured on a single Intel Arria 10 device.

Table 23. PMA Features of the Transceivers in Intel Arria 10 Devices

Feature	Capability	
Chip-to-Chip Data Rates	1 Gbps to 17.4 Gbps (Intel Arria 10 GX devices) 1 Gbps to 25.8 Gbps (Intel Arria 10 GT devices)	
Backplane Support	Drive backplanes at data rates up to 12.5 Gbps	
Optical Module Support	SFP+/SFP, XFP, CXP, QSFP/QSFP28, CFP/CFP2/CFP4	
Cable Driving Support	SFP+ Direct Attach, PCI Express over cable, eSATA	
Transmit Pre-Emphasis	4-tap transmit pre-emphasis and de-emphasis to compensate for system channel loss	
Continuous Time Linear Equalizer (CTLE)	Dual mode, high-gain, and high-data rate, linear receive equalization to compensate for system channel loss	
Decision Feedback Equalizer (DFE)	7-fixed and 4-floating tap DFE to equalize backplane channel loss in the presence of crosstalk and noisy environments	
Variable Gain Amplifier	Optimizes the signal amplitude prior to the CDR sampling and operates in fixed and adaptive modes	
Altera Digital Adaptive Parametric Tuning (ADAPT)	Fully digital adaptation engine to automatically adjust all link equalization parameters—including CTLE, DFE, and variable gain amplifier blocks—that provide optimal link margin without intervention from user logic	
Precision Signal Integrity Calibration Engine (PreSICE)	Hardened calibration controller to quickly calibrate all transceiver control parameters on power-up, which provides the optimal signal integrity and jitter performance	
Advanced Transmit (ATX) PLL	Low jitter ATX (LC tank based) PLLs with continuous tuning range to cover a wide range of standard and proprietary protocols	
Fractional PLLs	On-chip fractional frequency synthesizers to replace on-board crystal oscillators and reduce system cost	
Digitally Assisted Analog CDR	Superior jitter tolerance with fast lock time	
Dynamic Partial Reconfiguration	Allows independent control of the Avalon memory-mapped interface of each transceiver channel for the highest transceiver flexibility	
Multiple PCS-PMA and PCS- PLD interface widths	8-, 10-, 16-, 20-, 32-, 40-, or 64-bit interface widths for flexibility of deserialization width, encoding, and reduced latency	

PCS Features

This table summarizes the Intel Arria 10 transceiver PCS features. You can use the transceiver PCS to support a wide range of protocols ranging from 1 Gbps to 25.8 Gbps.





PCS	Description
Standard PCS	 Operates at a data rate up to 12 Gbps Supports protocols such as PCI-Express, CPRI 4.2+, GigE, IEEE 1588 in Hard PCS Implements other protocols using Basic/Custom (Standard PCS) transceiver configuration rules.
Enhanced PCS	 Performs functions common to most serial data industry standards, such as word alignment, encoding/decoding, and framing, before data is sent or received off-chip through the PMA Handles data transfer to and from the FPGA fabric Handles data transfer internally to and from the PMA Provides frequency compensation Performs channel bonding for multi-channel low skew applications
PCIe Gen3 PCS	 Supports the seamless switching of Data and Clock between the Gen1, Gen2, and Gen3 data rates Provides support for PIPE 3.0 features Supports the PIPE interface with the Hard IP enabled, as well as with the Hard IP bypassed

Related Information

- PCIe Gen1, Gen2, and Gen3 Hard IP on page 26
- Interlaken Support on page 26
- 10 Gbps Ethernet Support on page 26

PCS Protocol Support

This table lists some of the protocols supported by the Intel Arria 10 transceiver PCS. For more information about the blocks in the transmitter and receiver data paths, refer to the related information.

Protocol	Data Rate (Gbps)	Transceiver IP	PCS Support
PCIe Gen3 x1, x2, x4, x8	8.0	Native PHY (PIPE)	Standard PCS and PCIe Gen3 PCS
PCIe Gen2 x1, x2, x4, x8	5.0	Native PHY (PIPE)	Standard PCS
PCIe Gen1 x1, x2, x4, x8	2.5	Native PHY (PIPE)	Standard PCS
1000BASE-X Gigabit Ethernet	1.25	Native PHY	Standard PCS
1000BASE-X Gigabit Ethernet with IEEE 1588v2	1.25	Native PHY	Standard PCS
10GBASE-R	10.3125	Native PHY	Enhanced PCS
10GBASE-R with IEEE 1588v2	10.3125	Native PHY	Enhanced PCS
10GBASE-R with KR FEC	10.3125	Native PHY	Enhanced PCS
10GBASE-KR and 1000BASE-X	10.3125	1G/10GbE and 10GBASE-KR PHY	Standard PCS and Enhanced PCS
Interlaken (CEI-6G/11G)	3.125 to 17.4	Native PHY	Enhanced PCS
SFI-S/SFI-5.2	11.2	Native PHY	Enhanced PCS
10G SDI	10.692	Native PHY	Enhanced PCS
	•		continued



Protocol	Data Rate (Gbps)	Transceiver IP	PCS Support
CPRI 6.0 (64B/66B)	0.6144 to 10.1376	Native PHY	Enhanced PCS
CPRI 4.2 (8B/10B)	0.6144 to 9.8304	Native PHY	Standard PCS
OBSAI RP3 v4.2	0.6144 to 6.144	Native PHY	Standard PCS
SD-SDI/HD-SDI/3G-SDI	0.143 ⁽¹²⁾ to 2.97	Native PHY	Standard PCS

Related Information

Intel Arria 10 Transceiver PHY User Guide

Provides more information about the supported transceiver protocols and PHY IP, the PMA architecture, and the standard, enhanced, and PCIe Gen3 PCS architecture.

SoC with Hard Processor System

Each SoC device combines an FPGA fabric and a hard processor system (HPS) in a single device. This combination delivers the flexibility of programmable logic with the power and cost savings of hard IP in these ways:

- Reduces board space, system power, and bill of materials cost by eliminating a discrete embedded processor
- Allows you to differentiate the end product in both hardware and software, and to support virtually any interface standard
- Extends the product life and revenue through in-field hardware and software updates

⁽¹²⁾ The 0.143 Gbps data rate is supported using oversampling of user logic that you must implement in the FPGA fabric.



Table 24. **Improvements in 20 nm HPS**

This table lists the key improvements of the 20 nm HPS compared to the 28 nm HPS.

Advantages/ Improvements	Description
Increased performance and overdrive capability	While the nominal processor frequency is 1.2 GHz, the 20 nm HPS offers an "overdrive" feature which enables a higher processor operating frequency. This requires a higher supply voltage value that is unique to the HPS and may require a separate regulator.
Increased processor memory bandwidth and DDR4 support	Up to 64-bit DDR4 memory at 2,400 Mbps support is available for the processor. The hard memory controller for the HPS comprises a multi-port front end that manages connections to a single port memory controller. The multi-port front end allows logic core and the HPS to share ports and thereby the available bandwidth of the memory controller.
Flexible I/O sharing	 An advanced I/O pin muxing scheme allows improved sharing of I/O between the HPS and the core logic. The following types of I/O are available for SoC: 17 dedicated I/Os—physically located inside the HPS block and are not accessible to logic within the core. The 17 dedicated I/Os are used for HPS clock, resets, and interfacing with boot devices, QSPI, and SD/MMC. 48 direct shared I/O—located closest to the HPS block and are ideal for high speed HPS peripherals such as EMAC, USB, and others. There is one bank of 48 I/Os that supports direct sharing where the 48 I/Os can be shared 12 I/Os at a time. Standard (shared) I/O—all standard I/Os can be shared by the PPS peripherals and any logic within the core. For designs where more than 48 I/Os are required to fully use all the peripherals in the HPS, these I/Os can be connected through the core logic.
EMAC core	Three EMAC cores are available in the HPS. The EMAC cores enable an application to support two redundant Ethernet connections; for example, backplane, or two EMAC cores for managing IEEE 1588 time stamp information while allowing a third EMAC core for debug and configuration. All three EMACs can potentially share the same time stamps, simplifying the 1588 time stamping implementation. A new serial time stamp interface allows core logic to access and read the time stamp values. The integrated EMAC controllers can be connected to external Ethernet PHY through the provided MDIO or I ² C interface.
On-chip memory	The on-chip memory is updated to 256 KB support and can support larger data sets and real time algorithms.
ECC enhancements	Improvements in L2 Cache ECC management allow identification of errors down to the address level. ECC enhancements also enable improved error injection and status reporting via the introduction of new memory mapped access to syndrome and data signals.
HPS to FPGA Interconnect Backbone	Although the HPS and the Logic Core can operate independently, they are tightly coupled via a high-bandwidth system interconnect built from high-performance ARM AMBA AXI bus bridges. IP bus masters in the FPGA fabric have access to HPS bus slaves via the FPGA-to-HPS interconnect. Similarly, HPS bus masters have access to bus slaves in the core fabric via the HPS-to-FPGA bridge. Both bridges are AMBA AXI-3 compliant and support simultaneous read and write transactions. Up to three masters within the core fabric can share the HPS SDRAM controller with the processor. Additionally, the processor can be used to configure the core fabric under program control via a dedicated 32-bit configuration port.
FPGA configuration and HPS booting	The FPGA fabric and HPS in the SoCs are powered independently. You can reduce the clock frequencies or gate the clocks to reduce dynamic power. You can configure the FPGA fabric and boot the HPS independently, in any order, providing you with more design flexibility.
Security	New security features have been introduced for anti-tamper management, secure boot, encryption (AES), and authentication (SHA).



Features of the HPS

The HPS has the following features:

- 1.2-GHz, dual-core ARM Cortex-A9 MPCore processor with up to 1.5-GHz via overdrive
 - ARMv7-A architecture that runs 32-bit ARM instructions, 16-bit and 32-bit
 Thumb instructions, and 8-bit Java byte codes in Jazelle style
 - Superscalar, variable length, out-of-order pipeline with dynamic branch prediction
 - Instruction Efficiency 2.5 MIPS/MHz, which provides total performance of 7500 MIPS at 1.5 GHz
- Each processor core includes:
 - 32 KB of L1 instruction cache, 32 KB of L1 data cache
 - Single- and double-precision floating-point unit and NEON media engine
 - CoreSight debug and trace technology
 - Snoop Control Unit (SCU) and Acceleration Coherency Port (ACP)
- 512 KB of shared L2 cache
- 256 KB of scratch RAM
- Hard memory controller with support for DDR3, DDR4 and optional error correction code (ECC) support
- Multiport Front End (MPFE) Scheduler interface to the hard memory controller
- 8-channel direct memory access (DMA) controller
- QSPI flash controller with SIO, DIO, QIO SPI Flash support
- NAND flash controller (ONFI 1.0 or later) with DMA and ECC support, updated to support 8 and 16-bit Flash devices and new command DMA to offload CPU for fast power down recovery
- Updated SD/SDIO/MMC controller to eMMC 4.5 with DMA with CE-ATA digital command support
- 3 10/100/1000 Ethernet media access control (MAC) with DMA
- 2 USB On-the-Go (OTG) controllers with DMA
- 5 I²C controllers (3 can be used by EMAC for MIO to external PHY)
- 2 UART 16550 Compatible controllers
- 4 serial peripheral interfaces (SPI) (2 Master, 2 Slaves)
- 62 programmable general-purpose I/Os, which includes 48 direct share I/Os that allows the HPS peripherals to connect directly to the FPGA I/Os
- 7 general-purpose timers
- 4 watchdog timers
- Anti-tamper, Secure Boot, Encryption (AES) and Authentication (SHA)



The optional power reduction techniques in Intel Arria 10 devices include:

- SmartVID—a code is programmed into each device during manufacturing that allows a smart regulator to operate the device at lower core V_{CC} while maintaining performance
- **Programmable Power Technology**—non-critical timing paths are identified by the Intel Quartus Prime software and the logic in these paths is biased for low power instead of high performance
- **Low Static Power Options**—devices are available with either standard static power or low static power while maintaining performance

Furthermore, Intel Arria 10 devices feature Intel's industry-leading low power transceivers and include a number of hard IP blocks that not only reduce logic resources but also deliver substantial power savings compared to soft implementations. In general, hard IP blocks consume up to 90% less power than the equivalent soft logic implementations.

Incremental Compilation

The Intel Quartus Prime software incremental compilation feature reduces compilation time and helps preserve performance to ease timing closure. The incremental compilation feature enables the partial reconfiguration flow for Intel Arria 10 devices.

Incremental compilation supports top-down, bottom-up, and team-based design flows. This feature facilitates modular, hierarchical, and team-based design flows where different designers compile their respective design sections in parallel. Furthermore, different designers or IP providers can develop and optimize different blocks of the design independently. These blocks can then be imported into the top level project.

Document Revision History for Intel Arria 10 Device Overview

Document Version	Changes
2018.04.09	Updated the lowest V_{CC} from 0.83 V to 0.82 V in the topic listing a summary of the device features.

Date	Version	Changes
January 2018	2018.01.17	Updated the maximum data rate for HPS (Intel Arria 10 SX devices external memory interface DDR3 controller from 2,166 Mbps to 2,133 Mbps.
		Updated maximum frequency supported for half rate QDRII and QDRII + SRAM to 633 MHz in Memory Standards Supported by the Soft Memory Controller table.
		Updated transceiver backplane capability to 12.5 Gbps.
		Removed transceiver speed grade 5 in Sample Ordering Core and Available Options for Intel Arria 10 GX Devices figure.
	·	continued



September 2017 July 2017 July 2017 May 2017	2017.09.20 2017.07.13 2017.07.06 2017.05.08	 Removed package code 40, low static power, SmartVID, industrial, and military operating temperature support from Sample Ordering Core and Available Options for Intel Arria 10 GT Devices figure. Updated short reach transceiver rate for Intel Arria 10 GT devices to 25.8 Gbps. Removed On-Die Instrumentation — EyeQ and Jitter Margin Tool support from PMA Features of the Transceivers in Intel Arria 10 Devices table. Updated the maximum speed of the DDR4 external memory interface from 1,333 MHz/2,666 Mbps to 1,200 MHz/2,400 Mbps. Corrected the automotive temperature range in the figure showing the available options for the Intel Arria 10 GX devices from "-40°C to 100°C" to "-40°C to 125°C". Added automotive temperature option to Intel Arria 10 GX device family.
July 2017 July 2017	2017.07.13	1,333 MHz/2,666 Mbps to 1,200 MHz/2,400 Mbps. Corrected the automotive temperature range in the figure showing the available options for the Intel Arria 10 GX devices from "-40°C to 100°C" to "-40°C to 125°C". Added automotive temperature option to Intel Arria 10 GX device family.
July 2017	2017.07.06	available options for the Intel Arria 10 GX devices from "-40°C to 100°C" to "-40°C to 125°C". Added automotive temperature option to Intel Arria 10 GX device family.
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May 2017	2017.05.08	
		 Corrected protocol names with "1588" to "IEEE 1588v2". Updated the vertical migration table to remove vertical migration between Intel Arria 10 GX and Intel Arria 10 SX device variants. Removed all "Preliminary" marks.
March 2017	2017.03.15	 Removed the topic about migration from Intel Arria 10 to Intel Stratix 10 devices. Rebranded as Intel.
October 2016	2016.10.31	 Removed package F36 from Intel Arria 10 GX devices. Updated Intel Arria 10 GT sample ordering code and maximum GX transceiver count. Intel Arria 10 GT devices are available only in the SF45 package option with a maximum of 72 transceivers.
May 2016	2016.05.02	 Updated the FPGA Configuration and HPS Booting topic. Remove V_{CC} PowerManager from the Summary of Features, Power Management and Arria 10 Device Variants and packages topics. This feature is no longer supported in Arria 10 devices. Removed LPDDR3 from the Memory Standards Supported by the HPS Hard Memory Controller table in the Memory Standards Supported by Intel Arria 10 Devices topic. This standard is only supported by the FPGA. Removed transceiver speed grade 5 from the Device Variants and Packages topic for Arria 10 GX and SX devices.
February 2016	2016.02.11	 Changed the maximum Arria 10 GT datarate to 25.8 Gbps and the minimum datarate to 1 Gbps globally. Revised the state for Core clock networks in the Summary of Features topic. Changed the transceiver parameters in the "Summary of Features for Arria 10 Devices" table. Changed the transceiver parameters in the "Maximum Resource Counts for Arria 10 GT Devices" table. Changed the package availability for GT devices in the "Package Plan for Arria 10 GT Devices" table. Changed the package configurations for GT devices in the "Migration Capability Across Arria 10 Product Lines" figure. Changed transceiver parameters in the "Low Power Serial Transceivers" section. Changed the transceiver descriptions in the "Device Variants for the Arria 10 Device Family" table. Changed the "Sample Ordering Code and Available Options for Arria 10 GT Devices" figure. Changed the datarates for GT devices in the "PMA Features" section. Changed the datarates for GT devices in the "PCS Features" section.



Date	Version	Changes
December 2015	2015.12.14	Updated the number of M20K memory blocks for Arria 10 GX 660 from 2133 to 2131 and corrected the total RAM bit from 48,448 Kb to 48,408 Kb.
		Corrected the number of DSP blocks for Arria 10 GX 660 from 1688 to 1687 in the table listing floating-point arithmetic resources.
November 2015	2015.11.02	• Updated the maximum resources for Arria 10 GX 220, GX 320, GX 480, GX 660, SX 220, SX 320, SX 480, and SX 660.
		Updated resource count for Arria 10 GX 320, GX 480, GX 660, SX 320, SX 480, a SX 660 devices in Number of Multipliers in Intel Arria 10 Devices table.
		 Updated the available options for Arria 10 GX, GT, and SX. Changed instances of <i>Quartus II</i> to <i>Quartus Prime</i>.
June 2015	2015.06.15	Corrected label for Intel Arria 10 GT product lines in the vertical migration figure.
May 2015	2015.05.15	Corrected the DDR3 half rate and quarter rate maximum frequencies in the table that lists the memory standards supported by the Intel Arria 10 hard memory controller.
May 2015	2015.05.04	Added support for 13.5G JESD204b in the Summary of Features table. Added support for 13.5G JESD204b in the Summary of Features table.
		Added a link to Arria 10 GT Channel Usage in the Arria 10 GT Package Plan topic.
		Added a note to the table, Maximum Resource Counts for Arria 10 GT devices.
		Updated the power requirements of the transceivers in the Low Power Serial Transceivers topic.
January 2015	2015.01.23	Added floating point arithmetic features in the Summary of Features table.
		Updated the total embedded memory from 38.38 megabits (Mb) to 65.6 Mb.
		Updated the table that lists the memory standards supported by Intel Arria 10 devices.
		 Removed support for DDR3U, LPDDR3 SDRAM, RLDRAM 2, and DDR2. Moved RLDRAM 3 support from hard memory controller to soft memory controller. RLDRAM 3 support uses hard PHY with soft memory controller.
		Added soft memory controller support for QDR IV.
		Updated the maximum resource count table to include the number of hard memory controllers available in each device variant.
		Updated the transceiver PCS data rate from 12.5 Gbps to 12 Gbps.
		Updated the max clock rate of PS, FPP x8, FPP x16, and Configuration via HPS from 125 MHz to 100 MHz.
		Added a feature for fractional synthesis PLLs: PLL cascading.
		Updated the HPS programmable general-purpose I/Os from 54 to 62.
September 2014	2014.09.30	Corrected the 3 V I/O and LVDS I/O counts for F35 and F36 packages of Arria 10 GX.
		Corrected the 3 V I/O, LVDS I/O, and transceiver counts for the NF40 package of the Arria GX 570 and 660.
		Removed 3 V I/O, LVDS I/O, and transceiver counts for the NF40 package of the Arria GX 900 and 1150. The NF40 package is not available for Arria 10 GX 900 and 1150.
		continued